HOSTAFORM® C 13021 XAP®2

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POM copolymer Medium flow injection molding grade with reduced emissions especially for automotive interior application. Burning rate according to FMVSS 302 < 100 mm/min (1 mm thickness) Emission according to VDA 275 < 2 mg/kg (natural grades) Emission according to VDA 275 < 5 mg/kg (colored grades)

Product information

Resin Identification	POM		ISO 1043
Part Marking Code	>POM<		ISO 11469

Rheological properties

Melt volume-flow rate	12	cm^3/10min	ISO 1133
Temperature	374	°F	
Load	4.76	lb	
Molding shrinkage, parallel	2.0	%	ISO 294-4, 2577
Molding shrinkage, normal	1.8	%	ISO 294-4, 2577

Typical mechanical properties

Tensile modulus	399000	psi	ISO 527-1/-2
Tensile stress at yield, 50mm/min	9300	psi	ISO 527-1/-2
Tensile strain at yield, 50mm/min	9	%	ISO 527-1/-2
Nominal strain at break	25	%	ISO 527-1/-2
Flexural modulus	392000	psi	ISO 178
Tensile creep modulus, 1h	348000	psi	ISO 899-1
Tensile creep modulus, 1000h	174000	psi	ISO 899-1
Charpy impact strength, 23°C	95.1	ftlb/in^2	ISO 179/1eU
Charpy impact strength, -30°C	95.1	ftlb/in^2	ISO 179/1eU
Charpy notched impact strength, 23°C	3.09	ftlb/in^2	ISO 179/1eA
Charpy notched impact strength, -30°C	2.85	ftlb/in^2	ISO 179/1eA

Thermal properties

Melting temperature, 10°C/min	331	°F	ISO 11357-1/-3
Coefficient of linear thermal expansion (CLTE), parallel	0.67	E-4/°F	ISO 11359-1/-2
Coefficient of linear thermal expansion (CLTE), normal	0.667	E-4/°F	ISO 11359-1/-2

Flammability

FMVSS Class	B		ISO 3795 (FMVSS 302)
Burning rate, Thickness 1 mm	1.77	in/min	ISO 3795 (FMVSS 302)

Electrical properties

Relative permittivity, 100Hz	4		IEC 62631-2-1
Relative permittivity, 1MHz	4		IEC 62631-2-1
Dissipation factor, 100Hz	20	E-4	IEC 62631-2-1
Dissipation factor, 1MHz	50	E-4	IEC 62631-2-1
Volume resistivity	1E12	Ohm.m	IEC 62631-3-1
Surface resistivity	1E14	Ohm	IEC 62631-3-2
Electric strength	889	kV/in	IEC 60243-1
Comparative tracking index	600		IEC 60112

HOSTAFORM® C 13021 XAP®2

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Physical/Other properties

Humidity absorption, 2mm	0.2	%	Sim. to ISO 62
Water absorption, 2mm	0.65	%	Sim. to ISO 62
Density	0.0509	lb/in³	ISO 1183

Injection

Drying Recommended	no	
Drying Temperature	212	°F
Drying Time, Dehumidified Dryer	3 - 4	h
Processing Moisture Content	≤0.2	%
Melt Temperature Optimum	374	°F
Min. melt temperature	356	°F
Max. melt temperature	392	°F
Max. screw tangential speed	≤0.3	m/s
Mold Temperature Optimum	212	°F
Min. mold temperature	176	°F
Max. mold temperature	248	°F
Hold pressure range	8700 - 17400	psi
Hold Pressure Time (h is the max. wall thickness of the part in mm)	2h²-3	s
Back pressure	580	psi

Automotive

OEM	STANDARD	ADDITIONAL INFORMATION
Mercedes-Benz	DBL5404	BQF
VW Group	TL 524 76	

Characteristics

Processing	Injection Molding
Special characteristics	Low emissions

Additional information

Injection molding

Preprocessing

To achive low emission values pre drying using a recirculating air dryer (100 to 120 °C / max. 40 mm layer / 3 to 6 hours) is recommended.

Max. Water content 0,1 %

Processing

Standard injection moulding machines with three phase (15 to 25 D) plasticating screws will fit.

Postprocessing

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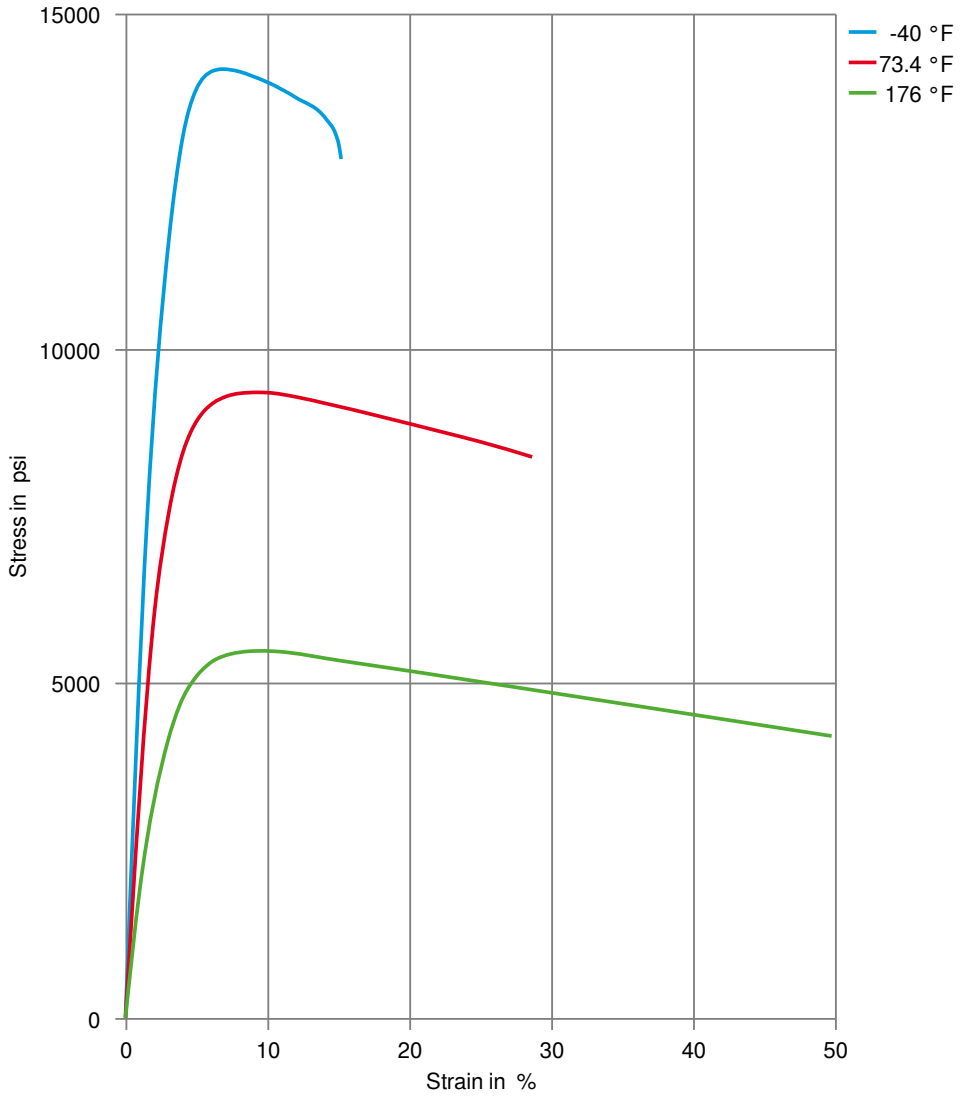
Conditioning e.g. moisturizing is not necessary.

Processing Notes

Pre-Drying

recommended

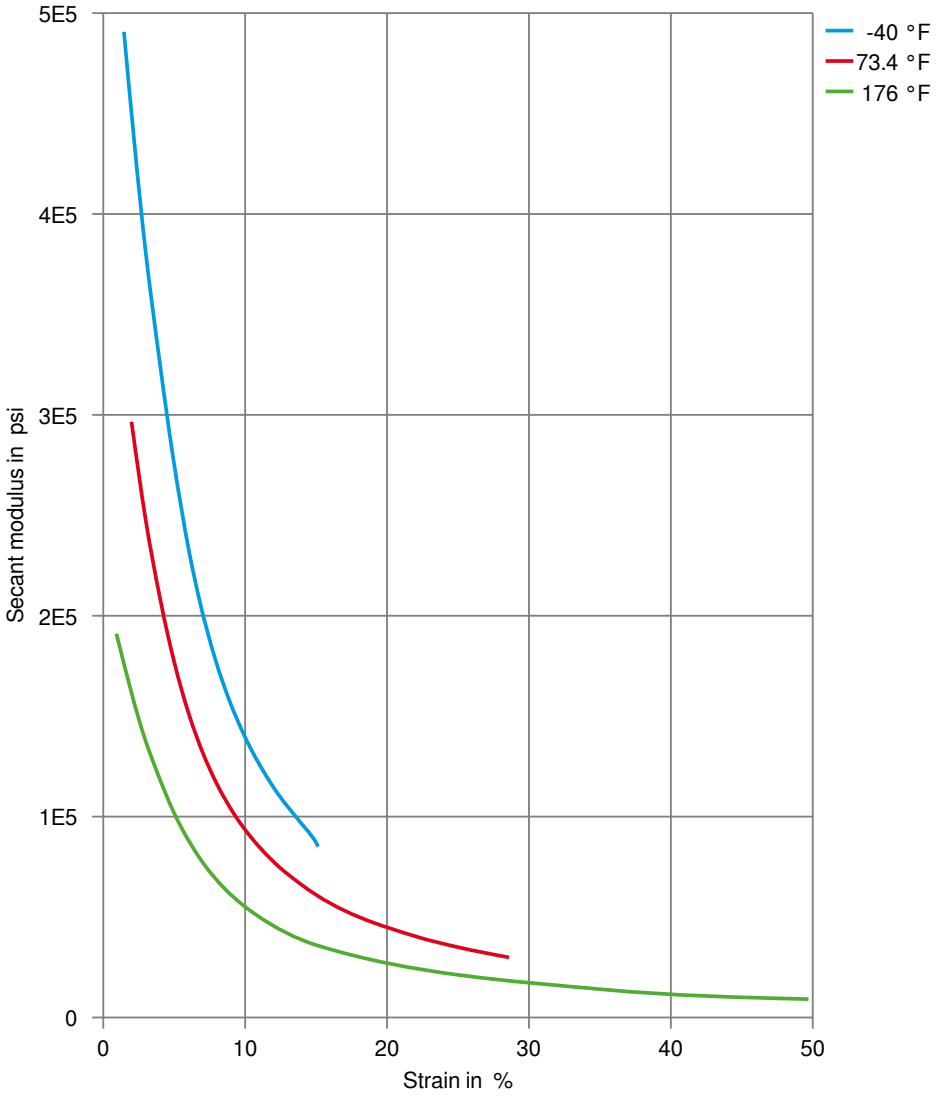
Stress-strain



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Secant modulus-strain



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